AS1431

Precision Adjustable Shunt Reference

Description

The AS1431 is a three-terminal adjustable shunt regulator providing a highly accurate 0.4% bandgap reference. The adjustable shunt regulator is ideal for a wide variety of linear applications that can be implemented using external components to obtain adjustable currents and voltages.

In the standard shunt configuration, the combination of low temperature coefficient (TC), sharp turn-on characteristics, low output impedance and programmable output voltage make this precision reference a perfect zener diode replacement.

The AS1431 is characterized to operate over the full automotive temperature range of –40 to 125°C and is now available in the SOT-23 (3L) TO92-3L, SOT-89, and SOIC-8,package.

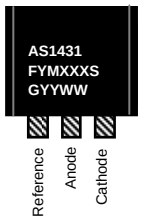
Features

- Temperature-compensated: 30 ppm/°C
- Trimmed 0.4% bandgap reference
- Internal amplifier with 150 mA capability
- Temperature range: Extended to –40 to125°C
- Low frequency dynamic output impedance: < 150 mΩ
- Low output noise
- Robust ESD protection

Pin Configuration — Top view

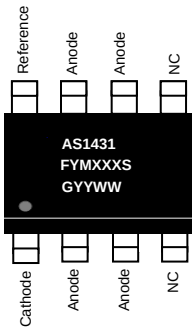
TO-92 (LP)

Line 1: Device
Line 2: Lot No. Code
F = Foundry Code
YMXXX = 5 character Lot no.
S = Split Code
Line 3: Date Code
G = Assembly Vendor Code
YY = Year
WW = Workweek



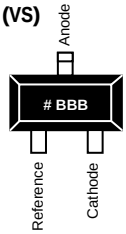
SOIC (D8)

Line 1: Device
Line 2: Lot No. Code
F = Foundry Code
YMXXX = 5 character Lot no.
S = Split Code
Line 3: Date Code
G = Assembly vendor code
YY = Year
WW = Workweek

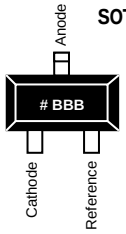


SOT-23/3L (VS)

Line 1: # BBB
- Device Number (single letter code)
BBB - Logbook Code
Note: # and BBB is supplied by Silicon Link

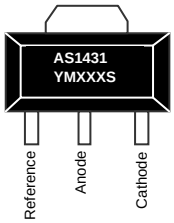


SOT-23/3L (VF)



SOT-89 (S)

Line 1: Device
Line 2: Lot No. Code
YMXXX = 5 character lot no. mark excluding 1st letter/ character of lot no.
S = Split Code



Ordering Information

AS1431 D R4 D8 13

Circuit Type:
Precision Adjustable Shunt Reference

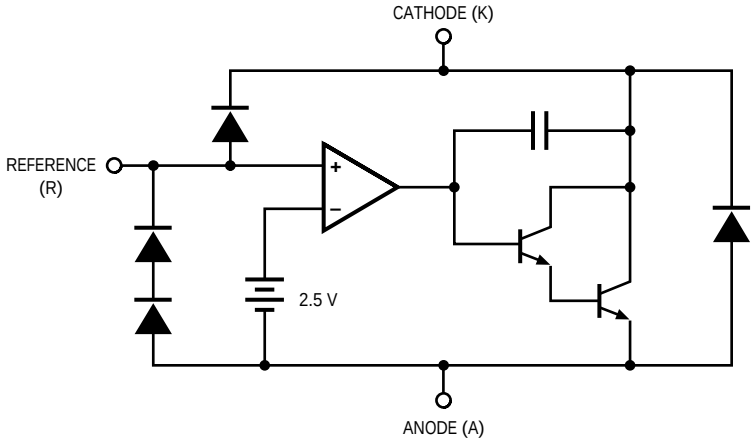
Temperature Range:
D = –40°C to +125°C

Bandgap Tolerance:
R4 = ±0.4%

Packaging Option:
A = Ammo Pack
B = Bulk
T = Tube
7 = Tape and Reel (7" Reel Dia)
13 = Tape and Reel (13" Reel Dia)

Package Style:
D8 = SOIC
VS = SOT-23/3L
VF = SOT-23/3L
LP = TO-92
S = SOT-89

Functional Block Diagram



Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Cathode-Anode Reverse Breakdown	V_{KA}	37	V
Anode-Cathode Forward Current	I_{AK}	1	A
Operating Cathode Current	I_{KA}	150	mA
Reference Input Current	I_{REF}	10	mA
Continuous Power Dissipation at 25°C	P_D		
TO-92		775	mW
8L SOIC		750	mW
SOT-89		1000	mW
SOT-23/3L		200	mW
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	–65 to 150	°C
Lead Temperature Soldering 10 Seconds	T_L	300	°C

Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Recommended Conditions

Parameter	Symbol	Rating	Unit
Cathode Voltage	V_{KA}	V_{REF} to 20	V
Cathode Current	I_K	10	mA

Typical Thermal Resistances

Package	θ_{JA}	θ_{JC}	Typical Derating
TO-92	160°C/W	80°C/W	6.3 mW/°C
SOIC	175°C/W	45°C/W	5.7 mW/°C
SOT-89	110°C/W	8°C/W	9.1 mW/°C
SOT-23/3L	575°C/W	150°C/W	1.7 mW/°C

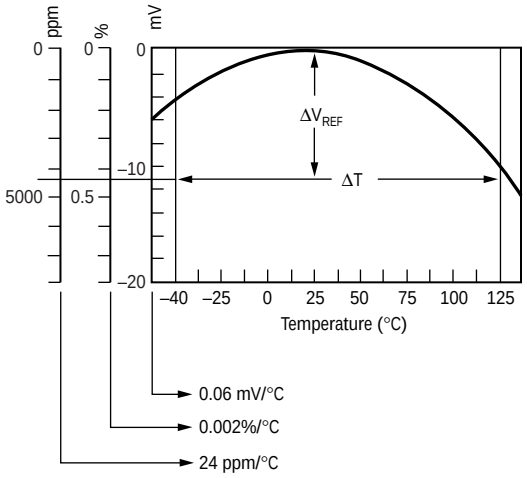
Electrical Characteristics

Electrical Characteristics are guaranteed over full junction temperature range (–40 to 125°C). Ambient temperature must be derated based on power dissipation and package thermal characteristics. The conditions are: $V_{KA} = V_{REF}$ and I_K = 10 mA unless otherwise stated.

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit	Circuit
Reference Voltage	V_{REF}	T_A = 25°C	2.490	2.500	2.510	V	1
		Over temp.	2.470		2.530	V	1
ΔV_{REF} with Temp*	TC			0.06	0.16	mV/°C	1
Ratio of Change in V_{REF} to Cathode Voltage	ΔV_{REF}	ΔV_K = 3 V to 36 V	–2	–1.1		mV/V	2
Reference Input Current	I_{REF}	R_1 = 10 k Ω; R_2 = ∞		0.7	1.9	µA	2
I_{REF} Temp Deviation	ΔI_{REF}	Over temp.		0.4	1.2	µA	2
Min I_K for Regulation	$I_{K(min)}$			0.4	1	mA	1
Off State Leakage	$I_{K(off)}$	V_{REF} = 0 V, V_{KA} = 36 V		0.04	500	nA	3
Dynamic Output Impedance	Z_{KA}	f ≤ 1 kHz I_K = 1 to 100 mA		0.15	0.2	Ω	1

*Calculating Average Temperature Coefficient (TC)

Average Temperature Coefficient



$$\bullet\ \text{TC in mV/°C} = \frac{\Delta V_{REF}\ (\text{mV})}{\Delta T_A}$$

$$\bullet\ \text{TC in \%/°C} = \frac{\left(\frac{\Delta V_{REF}}{V_{REF}\ \text{at}\ 25°C}\right) \text{X } 100}{\Delta T_A}$$

$$\bullet\ \text{TC in ppm/°C} = \frac{\left(\frac{\Delta V_{REF}}{V_{REF}\ \text{at}\ 25°C}\right) \text{X } 10^6}{\Delta T_A}$$

Test Circuits

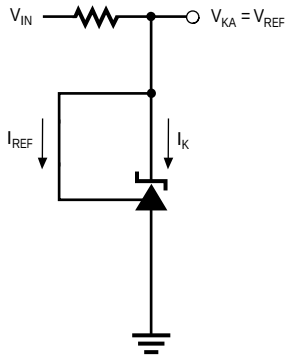


Figure 1a. Test Circuit 1

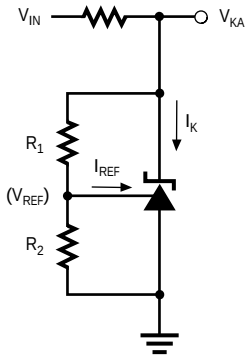


Figure 1b. Test Circuit 2

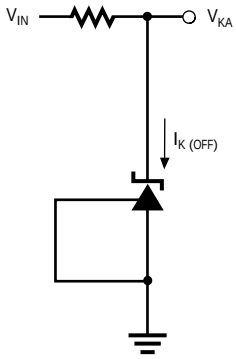


Figure 1c. Test Circuit 3

Typical Performance Curves

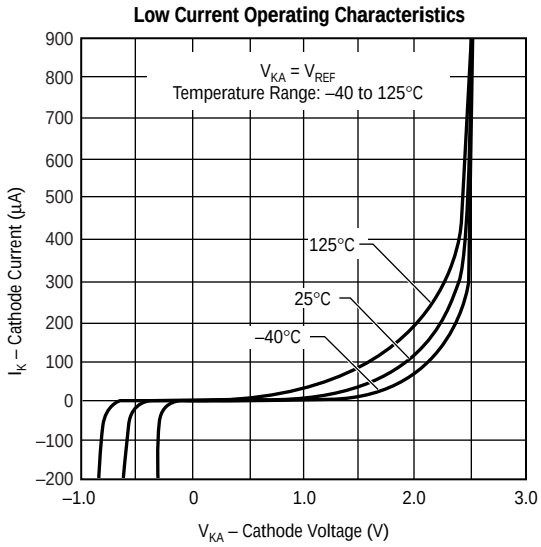


Figure 2

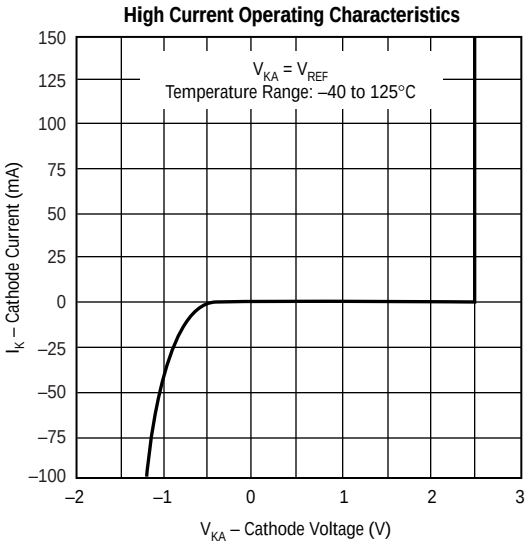


Figure 3

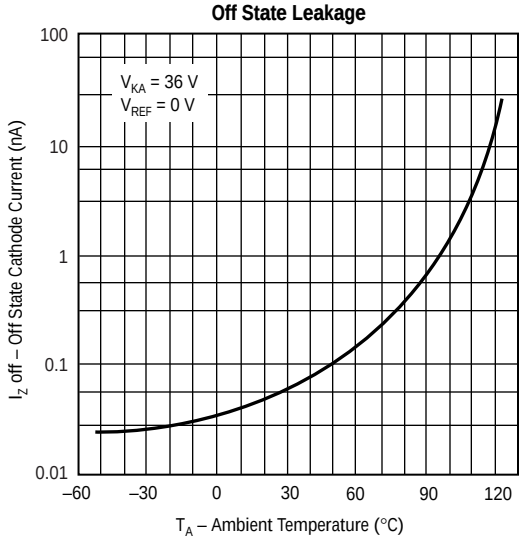


Figure 4

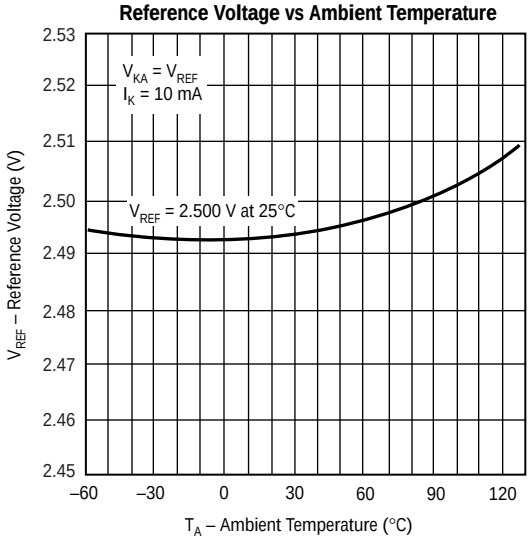


Figure 5

Typical Performance Curves

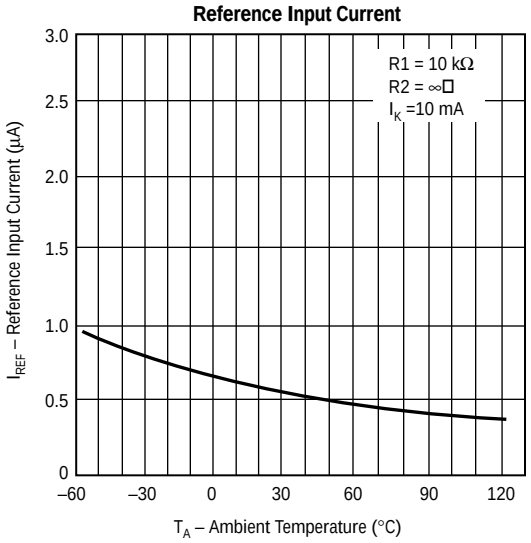


Figure 6

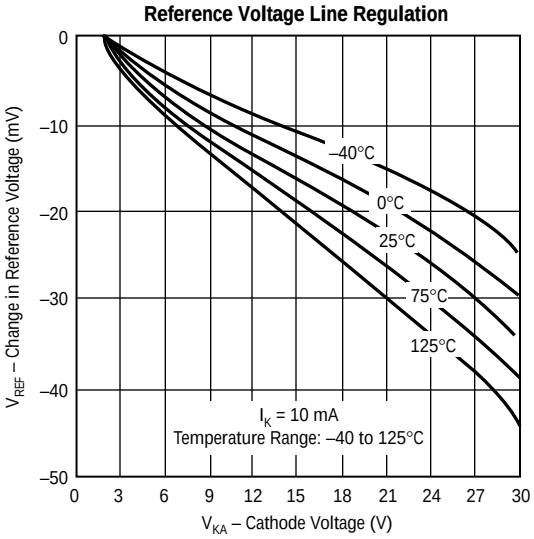


Figure 7

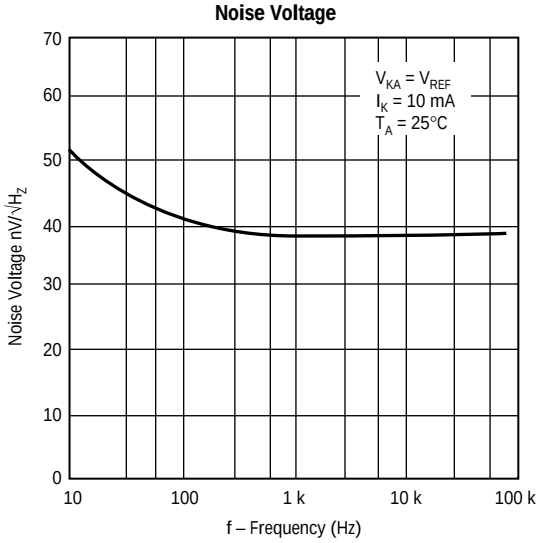


Figure 8

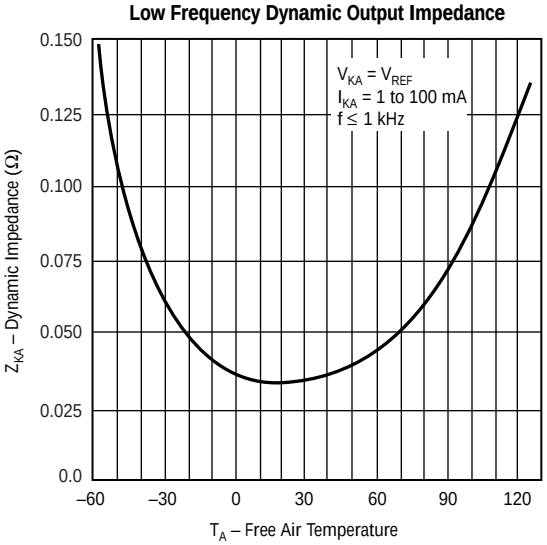


Figure 9

Typical Performance Curves

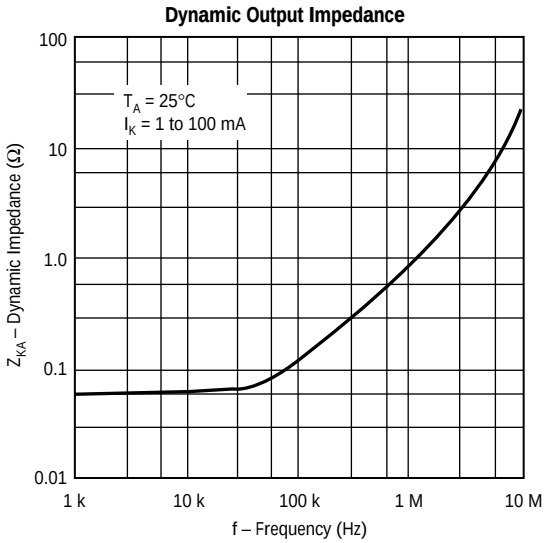


Figure 10

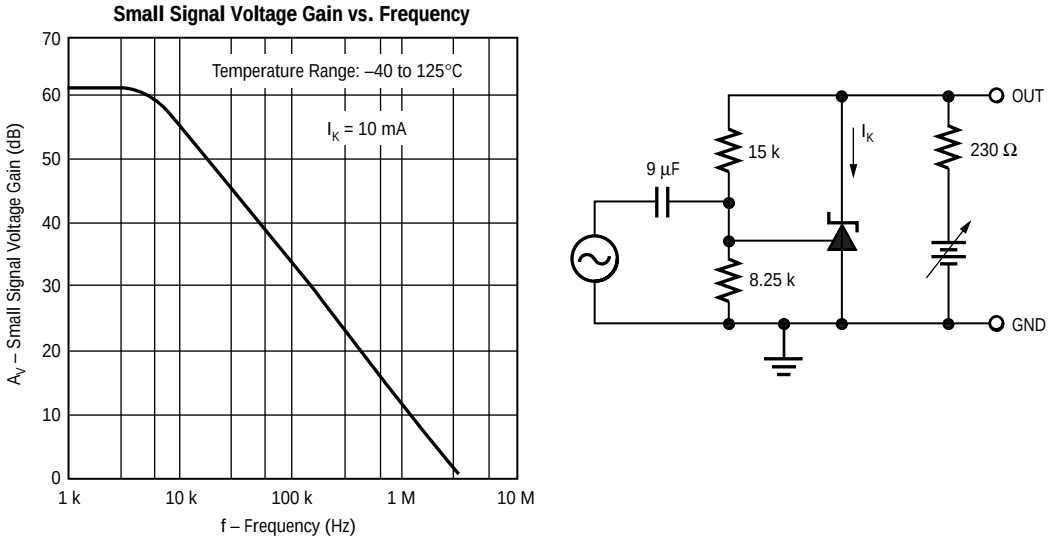


Figure 11

Typical Performance Curves

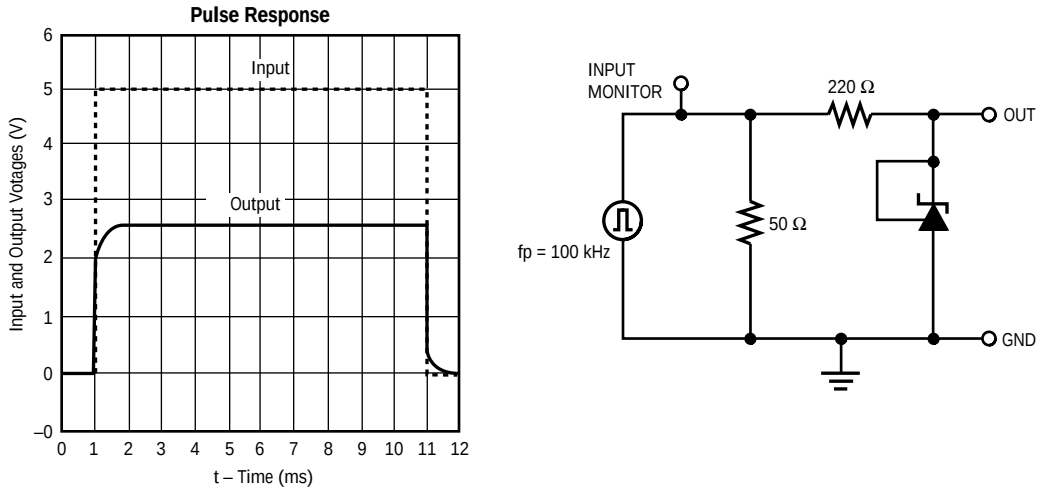


Figure 12

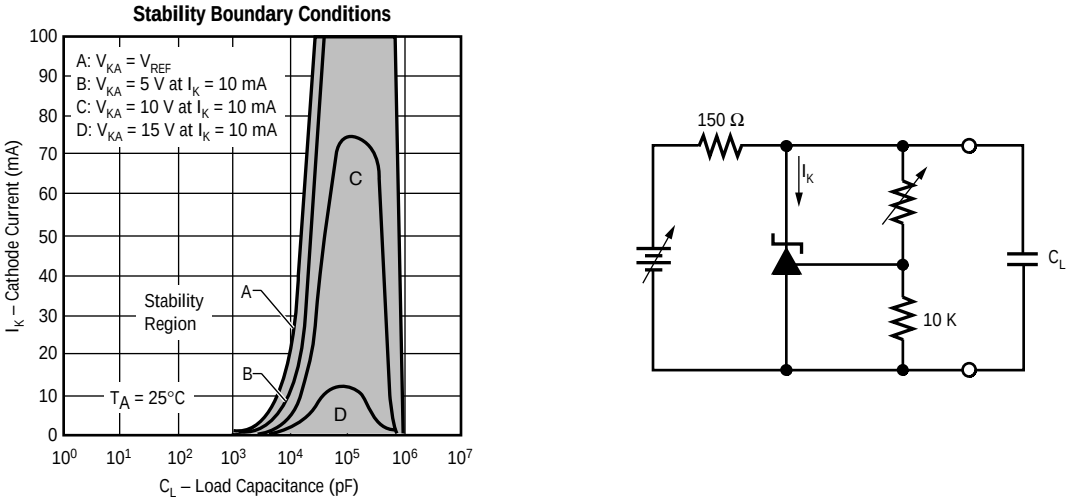
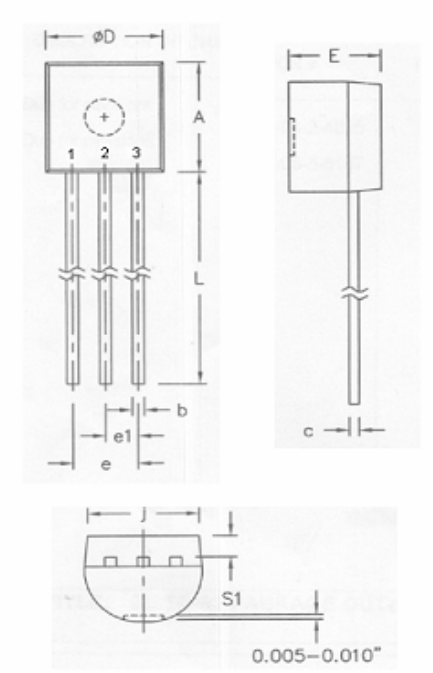


Figure 13

TO-92 Dimension

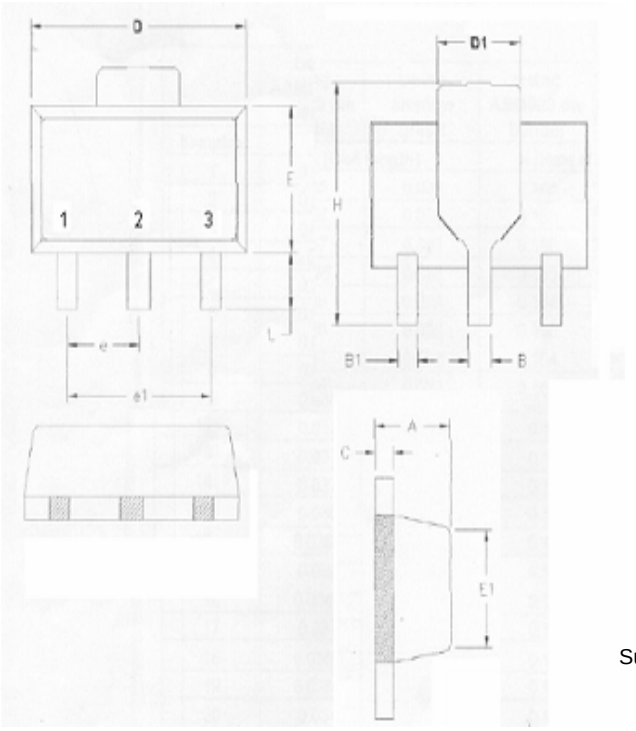


INCHES			
SYM	MIN	NOM	MAX
A	0.176	0.180	0.184
B	0.015	0.018	0.022
C	0.014	0.015	0.020
øD	0.176	0.180	0.184
e	0.098	0.100	0.102
e1	0.048	0.050	0.052
E	0.136	0.140	0.144
j	0.166	0.170	0.174
L	0.530	0.550	0.570
S1	0.031	0.035	0.039

*: Typical, Unit: inches

3-Lead TO-92 Plastic Package
SLI Package Code: LP

SOT-89 Dimension

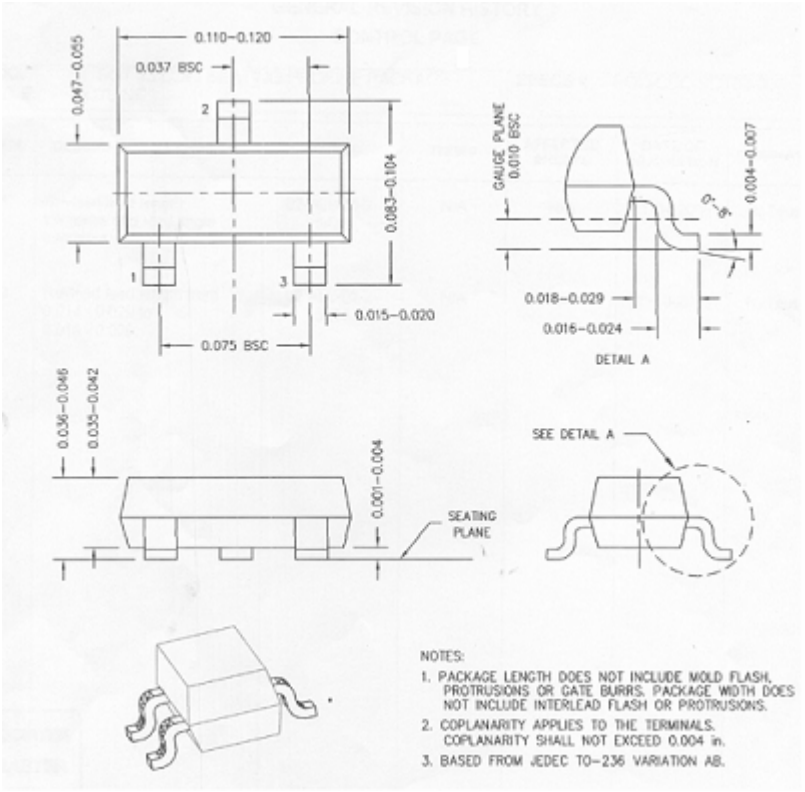


INCHES		
SYM	MIN	NOM
A	0.055	0.063
B	0.017	0.022
B1	0.014	0.019
C	0.014	0.017
D	0.173	0.181
D1	0.066	0.070
E	0.090	0.099
E1	0.084	0.086
e	0.059	
e1	0.118	
H	0.155	0.167
L	0.029	0.041

*: Typical, Unit: inches

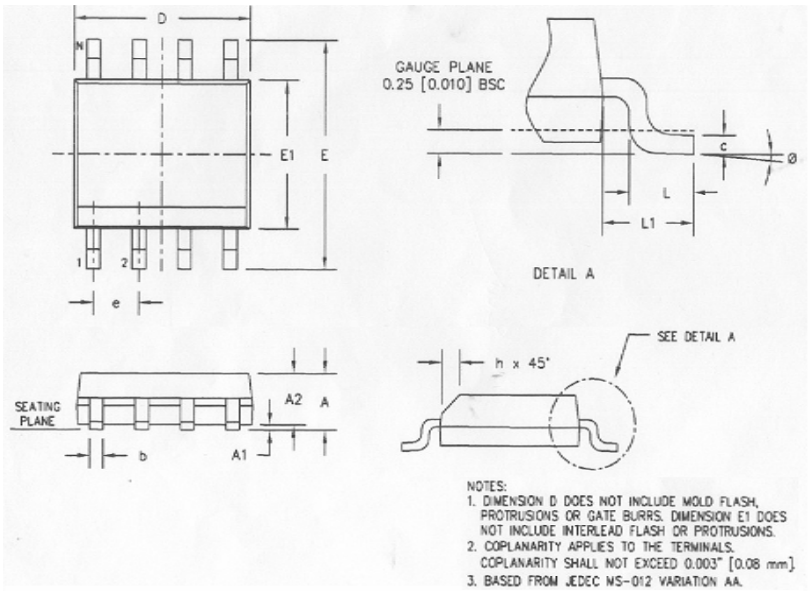
3-Lead SOT-89 Plastic
Surface Mounted Package
SLI Package Code: S

SOT-23 Dimension



3-Lead SOT-23 Plastic
Surface Mounted Package
SLI Package Code: VS

SOIC 8L Dimension



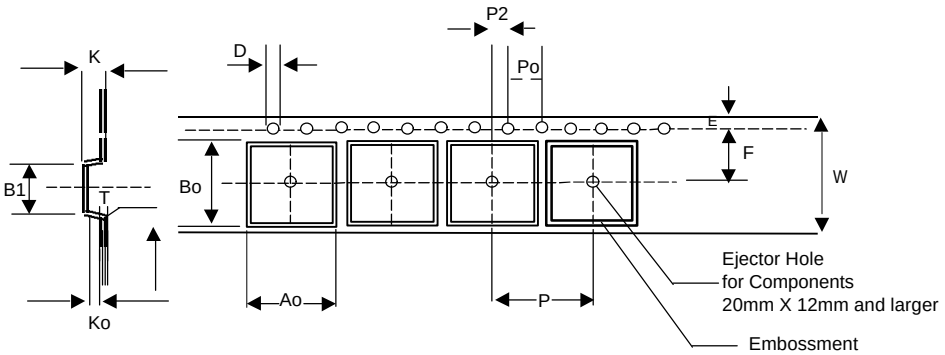
	DIMENSION IN INCHES			DIMENSION IN MM		
SYM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.059	0.062	0.065	1.50	1.57	1.65
A1	0.004	0.008	0.010	0.10	0.20	0.25
A2	0.051	0.054	0.057	1.30	1.37	1.45
b	0.013	0.016	0.020	0.33	0.41	0.51
c	0.007	0.008	0.010	0.18	0.20	0.25
D	0.191	0.193	0.195	4.85	4.90	4.95
E1	0.151	0.153	0.155	3.84	3.89	3.94
E	0.228	0.234	0.240	5.79	5.94	6.10
e		0.050			1.27	
L	0.020	0.024	0.032	0.51	0.51	0.81
L1	0.039	0.041	0.043	0.99	1.04	1.09
Ø	0*	-	B*	0*	-	B*
h	0.011	0.015	0.019	0.28	0.38	0.48

8-Lead SOIC Plastic
Surface Mounted Package
SLI Package Code: D8

Package Mechanical Drawing

Surface Mountable Tape & Reel Specifications in mm (inch)

(SOIC, SOT-89, SOT-23)



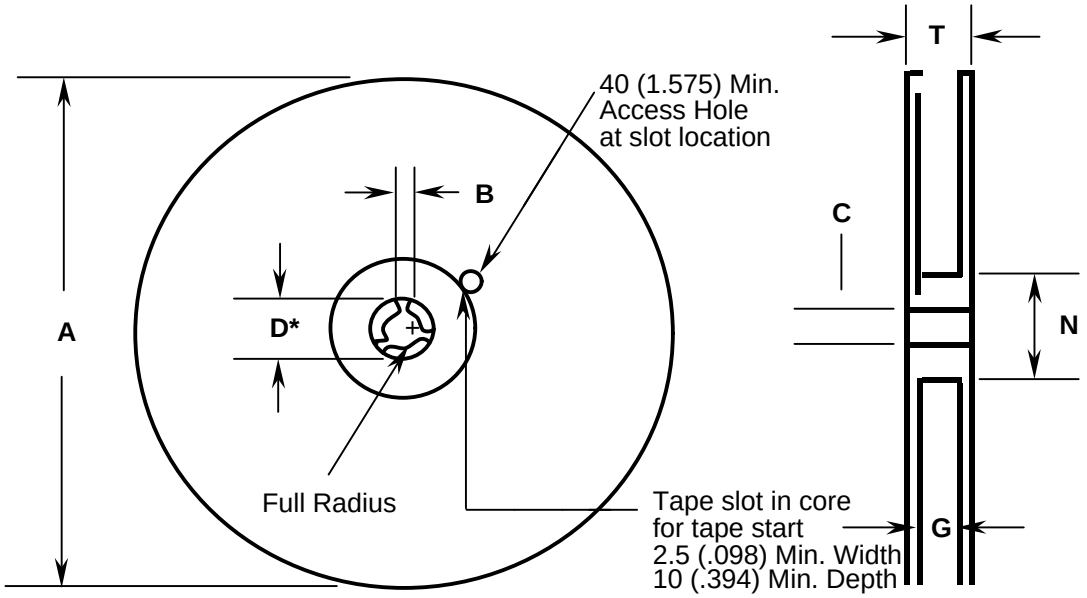
User direction of feed

Tape Size (W)	D	E	P0	T (Max)	A0, B0, K0	T1 (Max)	Constant
8, 12, 16, 24mm	1.55±0.05 (.061±.002)	1.75±0.10 (.069±.004)	4.0±0.10 (.157±.004)	0.400 (.016)	See Note	0.100 (.004)	Dimensions

Tape Size (W)	B1 Max.	D1 Min.	F	K Max.	P2	
8 mm	4.2 (.165)	1.0 (.039)	3.5±0.05 (.138±.002)	2.4 (.094)	2.0±.05	
12 mm	8.2 (.323)	1.5 (.059)	5.5±0.05 (.217±.002)	4.5 (.177)	.079±.002	Variable Dimensions

Per Package Requirement					
Components		Tape Width (W) mm	Cavity Pitch (P) mm	Devices per Reel	
				7" Reel	13" Reel
SOIC	8L	12	8	-	2500
SOT-23	3L	8	4	3000	-
SOT-89	3L	12	8	-	2500

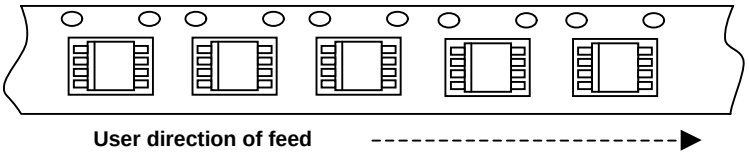
Note: Ao Bo Ko are determined by component size. The clearance between the component and the cavity must be within 0.05 [.002] min. to 0.50 [.020] max. for 8mm tape, 0.05 [.002] min to 0.65 [.026] max for 12mm tape.



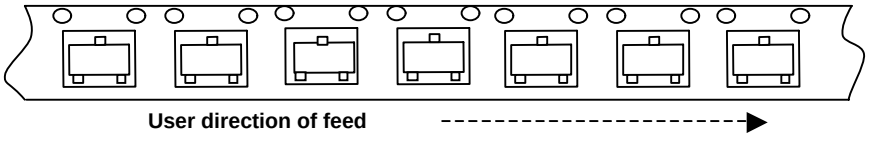
REEL DIMENSIONS							
Tape Size	A Max.	B Min.	C	D* Min.	N Min.	G	T Max.
8mm	330 (12.992)	1.5 (.059)	13.0±0.20 (.152±.008)	20.2 (.795)	50 (1.973)	$8.4^{\ 0.0}_{\pm 1.5}$ $(.331^{\ 0.0}_{\pm .059})$	14.4 (.567)
12mm	330 (12.992)	1.5 (.059)	13.0±0.20 (.152±.008)	20.2 (.795)	50 (1.973)	$12.4^{\ 0.0}_{\pm 2.0}$ $(.488^{\ 0.0}_{\pm .078})$	14.4 (.567)

MECHANICAL POLARIZATION

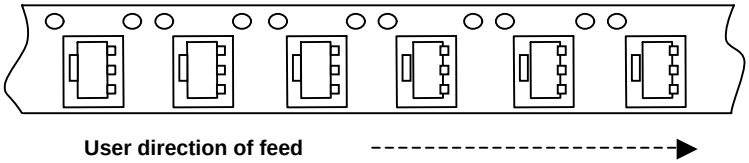
SOIC DEVICES



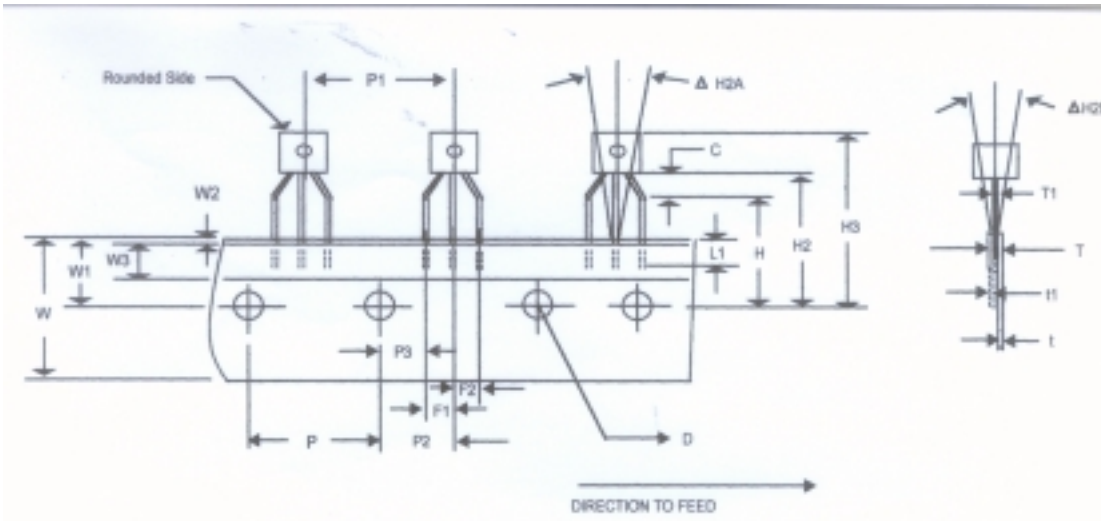
SOT 23 3L DEVICE



SOT 89 DEVICE



TO-92 Ammo Pack Specifications



SYM	DESCRIPTION	NOMINAL		TOLERANCES			
BOL		VALUE		min		max	
		mm	inch	mm	inch	mm	inch
D	Feed Hole Diameter	4.0	0.157	3.8	0.150	4.2	0.165
T1 (POD)	Component Lead Thickness	0.405	0.016	0.36	0.014	0.45	0.018
F1/F2	Lead Pitch (Left / Right)	2.54	0.100	2.4	0.094	2.8	0.110
C	Bottom of Component to Seating Plane	2.50	0.098	1.50	0.059	4.00	0.157
W1	Edge to Sprocket Hole Center	9.0	0.354	8.50	0.335	9.50	0.374
H2A	Deflection (Left or Right)	0.50	0.020	0	0	0.50	0.020
H2B	Deflection (Front or Rear)	1.0	0.039	0	0	1.0	0.039
H2 (H +C)	Feed Hole to Bottom of Component	18.5	0.728	17.00	0.669	20.50	0.087
H	Height of Seating Plane	16	0.630	15.5	0.610	16.5	0.650
H3	Feed Hole Center to Overall Transistor Height	27.75	1.092	23.5	0.925	32.0	1.260
L	Defective Unit Clipped Dimension	-	-	-	-	11.0	0.433
L1	Leadwire Enclosure	2.50	0.098	2.50	0.098	-	-
P	Feed Hole Pitch	12.7	0.500	12.40	0.488	13.0	0.512
P2	Center of Feed Hole to Center Lead	6.35	0.250	6.0	0.234	6.75	0.266
P3 (P2-F1)	First Lead Spacing Dimension	3.75	0.148	3.6	0.142	3.95	0.156
P1	Center Lead to Center Lead	12.7	0.500	12.2	0.500	13.2	0.520
t1	Adhesive Tape Thickness	0.18	0.007	0.16	0.006	0.20	0.008
T (t+t1+T1)	Overall Taped Package Thickness	-	-	-	-	1.55	0.061
t	Carrier Strip Thickness	0.37	0.015	0.27	0.011	0.47	0.018
W	Carrier Strip Width (18mm)	18.00	0.709	17.5	0.689	19.0	0.748
W3	Adhesive Tape Width (6mm)	6.00	0.236	5.5	0.217	6.3	0.248
W2	Adhesive Tape Position	0.25	0.010	0	0	0.50	0.020

TO-92 Ammo Pack Requirement			
Components		Tape Width (W) mm	Fan Fold Box
TO-92	3L	18	2000